

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
TAKESHI AIZAWA	06/04/2014
SATOSHI MORIKAWA	06/03/2014
YOSHIHIRO UCHIYAMA	06/06/2014
KAZUAKI TAKEDA	06/06/2014
TAKASHI TONOSAKI	06/10/2014

RECEIVING PARTY DATA

Name:	AUTONETWORKS TECHNOLOGIES, LTD
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PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	14373189

CORRESPONDENCE DATA

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PATENT

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NAME OF SUBMITTER: GERALD E. HESPOS

SIGNATURE: /Gerald E. Hespos/

DATE SIGNED: 07/18/2014

Total Attachments: 1

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ASSIGNMENT

In consideration of the sum of One Dollar (\$1.00), and of other good and valuable consideration paid to the undersigned by the Assignees, 1) AUTONETWORKS TECHNOLOGIES, LTD., a corporation organized under the laws of Japan, located at 1-14, Nishisuehiro-cho, Yokkaichi-shi, Mie 510-8503 JAPAN, 2) SUMITOMO WIRING SYSTEMS, LTD., a corporation organized under the laws of Japan, located at 1-14, Nishisuehiro-cho, Yokkaichi-shi, Mie 510-8503 JAPAN and 3) SUMITOMO ELECTRIC INDUSTRIES, LTD., a corporation organized under the laws of Japan, located at 5-33, Kitahama 4-chome, Chuo-ku, Osaka-shi, Osaka 541-0041 JAPAN, receipt whereof is hereby acknowledged, the undersigned by these presents hereby sells, assigns, transfers and sets over unto the said assignees the entire right, title and interest in and to the invention or improvement entitled "Terminal Fitting", said invention being fully described and/or claimed in the application for Letters Patent of the United States of America, executed this date, in and for the United States and all foreign countries, the same to be held and enjoyed by said assignees, its successors, assigns or other legal representatives, to the full ends of the terms for which all Letters Patent therefor may be granted, as fully and entirely as the same would have been held and enjoyed by the undersigned if this assignment and sale had not been made.

And Said Assignees Are Hereby Authorized to make application for and to receive Letters Patent for said invention in any of said countries at its election.

And By This Covenant The Undersigned will execute or procure any further necessary assurance of title to said invention and Letters Patent; and at any time, upon the request and at the expense of said assignees, will execute and deliver any and all papers that may be necessary or desirable to perfect the title to said invention or any Letters Patent which may be granted therefor to said Assignees, its successors, assigns or other legal representatives, and, upon the request and at the expense of said assignees, will execute any additional or divisional applications for patents for said invention, or any part or parts thereof, and for the reissue of any Letters Patent to be granted therefor, and will make all rightful oaths and do all lawful acts requisite for procuring the same or for aiding therein, without further compensation, but at the expense of said assignees, its successors, assigns or other legal representatives.

And The Commissioner Of Patents Is Hereby Authorized And Requested to issue any and all Letters Patent of the United States for said invention, to said assignees.

June 24, 2014
Date

Takeshi Aizawa
Takeshi AIZAWA

June 3, 2014
Date

Satoshi Morikawa
Satoshi MORIKAWA

June 6, 2014
Date

Yoshihiro Uchiyama
Yoshihiro UCHIYAMA

June 6, 2014
Date

Kazuaki Takeda
Kazuaki TAKEDA

June 10, 2014
Date

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